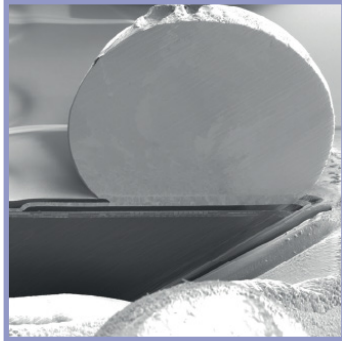


DUAL BEAM PLASMA FIB/SEM

- LARGE AREA FIB CROSS-SECTIONING
- LARGE AREA DE-PROCESSING
- (S)TEM SAMPLE PREPERATION
- LARGE AREA TRENCHING FOR FIB-CE
- EDS AND EBSD SAMPLE PREPERATION AND ANALYSIS

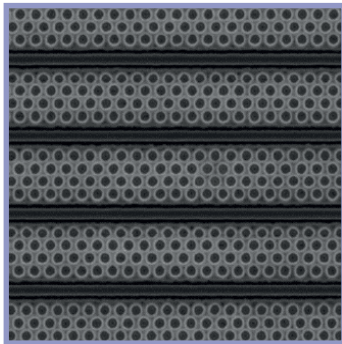


DUAL BEAM PLASMA FIB/SEM



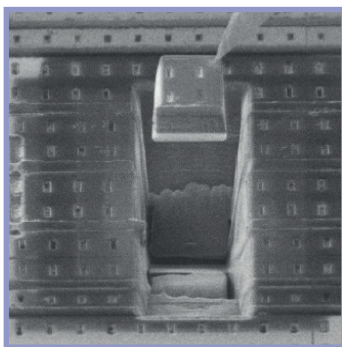
LARGE AREA FIB CROSS-SECTIONING

- MultiChem integrated gas delivery system
- Auto Rocking Mill to prevent curtaining
- Up to hundreds of μm
- Large area slice & view ($300\ \mu\text{m} \times 300\ \mu\text{m}$)
- Essential tool for 3D device FA



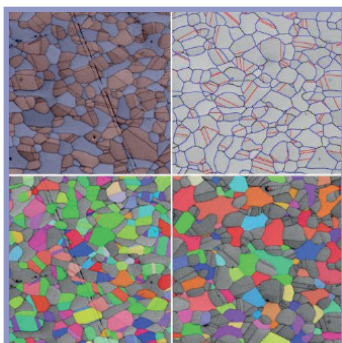
LARGE AREA DE-PROCESSING

- $100\ \mu\text{m} \times 100\ \mu\text{m}$ de-processing
- Layer-by-layer de-processing down to 7nm process node
- Damage free single layer exposure
- Secondary electron auto endpoint detection
- Only reliable solution for sub 20nm process nodes



(S)TEM SAMPLE PREP. AND LARGE AREA TRENCHING FOR FIB-CE

- Down to $\sim 30\text{nm}$ lamella thickness
- Planar TEM lamella preparation
- Large area stair step trenching for back side FIB Circuit Edit
- System capable of performing FIB Circuit Edits
- NEXS CAD Navigation for Circuit Edit



EDS AND EBSD SAMPLE PREPERATION AND ANALYSIS

- High sensitive EDS detector with $< 30\text{nm}$ spatial resolution
- Designed for light-element sensitivity and low KV analysis
- High-sensitivity and high-resolution material analysis
- Crystallographic and microstructural information for materials science, geological science and advanced device design